

SVT50N06T-VB Datasheet N-Channel 60-V (D-S) MOSFET

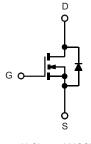
PRODUCT	SUMMARY	
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a
60	0.011 at V _{GS} = 10 V	60
00	0.013 at V _{GS} = 4.5 V	50

FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25	°C, unless other	vise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
	T _C = 25 °C	- I _D -	60	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C		50ª	
Pulsed Drain Current	·	I _{DM}	200	A
Continuous Source Current (Diode Conduction)		۱ _S	50ª	
Avalanche Current		I _{AS}	50	
Single Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AS}	125	mJ
Maximum Power Dissipation	T _C = 25 °C	Pn -	136	w
	T _A = 25 °C		3 ^b , 8.3 ^{b, c}	~ ~~
Operating Junction and Storage Temperature Range	·	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum lumation to Amelianta	$t \le 10 \text{ sec}$	R _{thJA}	15	18	
Maximum Junction-to-Ambient ^a	Steady State	• • • thJA	40	50	°C/W
Maximum Junction-to-Case		R _{thJC}	0.85	1.1	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. $t \le 10$ s.

$\begin{array}{ c c c c } \hline Parameter & Symbol & Test Conditions & Min. Typ.* Max. In Static & & & & & & & & & & & & & & & & & & &$	SPECIFICATIONS (T _J = 25 °C	, unless oth	erwise noted)					
$ \begin{array}{ c c c c } \hline \begin{tabular}{ c c c c } \hline \begin{tabular}{ c c c c } \hline \begin{tabular}{ c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Parameter	Symbol	Test Conditions	Min.	Typ.ª	Max.	Unit	
$ \begin{array}{c c c c c c } \hline Gate Threshold Voltage & V_{GS}(h) & V_{DS} = V_{GS}, h_{D} = 250 \ \mu\text{A} & 1 & 3 & \\ \hline \\ \hline \\ Gate-Body Leakage & l_{GSS} & V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V & \pm 100 & \\ \hline \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & 1 & \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & 1 & \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & & 1 & \\ \hline \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & & & 1 & \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & & & & 1 & \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & & & & & 1 & \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & & & & & & & & & \\ \hline \\ V_{DS} = 60 \ V, V_{GS} = 0 \ V & V_{J} = 125 \ ^{\circ} C & & & & & & & & & \\ \hline \\ On-State Drain Current^{b} & l_{D(on)} & V_{DS} = 5V \ V_{OS} = 5V \ V_{OS} = 10 \ V & l_{D} = 20 \ A & & & & & & & & \\ \hline \\ O_{S} = 10 \ V, l_{D} = 20 \ A \ V_{DS} = 15V \ l_{D} = 20 \ A & & & & & & & \\ \hline \\ V_{GS} = 10 \ V, l_{D} = 20 \ A \ V_{DS} = 15V \ V_{DS} = 10V \ V_{DS} = 15V \ V_{DS} = 10V \ V_{DS} = 15V \ V_{DS} = 10V \ V$	Static							
$ \begin{array}{c c c c c c } \mbox{Gate-Body Leakage} & I_{CSS} & V_{DS} = 0 \ V, \ V_{CS} = 2 \ 0 \ V & \ & \ & \ & \ & \ & \ & \ & \ & \$	Drain-Source Breakdown Voltage	V _{DS}	V_{GS} = 0 V, I _D = 250 µA	60			V	
$ \begin{array}{ c c c c c } \hline U_{DS} = 0 & V, V_{GS} = 0 & V & 1 & 1 \\ \hline V_{DS} = 60 & V, V_{GS} = 0 & V, T_J = 125 \ ^{\circ}{\rm C} & 50 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & $	Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1		3	v	
$ \begin{array}{ c c c c } \hline \mbox{Zero Gate Voltage Drain Current} & \mbox{I}_{DSS} & titmediated by the set of t$	Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
$ \begin{array}{ c c c c c c } \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V, I_{J} = 175 \ ^{\circ} C & 0 & 250 \\ \hline V_{DS} = 50 \ V, V_{GS} = 10 \ V & 60 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & $			V _{DS} = 60 V, V _{GS} = 0 V			1		
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	μA	
$ \begin{array}{ c c c c c c c c } \label{eq:constraint} \begin{tabular}{ c c c c c c c } \hline U_{GS} & = 10 \ V, \ I_{D} & = 20 \ A \\ \hline V_{GS} & = 10 \ V, \ I_{D} & = 20 \ A, \ T_{J} & = 125 \ ^{\circ} C \\ \hline 0.014 & [1] \\ \hline V_{GS} & = 10 \ V, \ I_{D} & = 20 \ A, \ T_{J} & = 175 \ ^{\circ} C \\ \hline 0.018 & [1] \\ \hline V_{GS} & = 10 \ V, \ I_{D} & = 20 \ A, \ T_{J} & = 175 \ ^{\circ} C \\ \hline 0.018 & [1] \\ \hline V_{GS} & = 10 \ V, \ I_{D} & = 20 \ A, \ T_{J} & = 175 \ ^{\circ} C \\ \hline 0.018 & [1] \\ \hline V_{GS} & = 10 \ V, \ I_{D} & = 20 \ A, \ T_{J} & = 175 \ ^{\circ} C \\ \hline 0.018 & [1] \\ \hline 0.010 & [1] \\ 0$			V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250		
$ \begin{array}{ c c c c c } \label{eq:result} Partial Pa$	On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			А	
$ \begin{array}{ c c c c } \hline Prain-Source On-State Resistanceb & R_{DS(on)} & \hline V_{GS} = 10 V, I_{D} = 20 A, T_{J} = 175 \ ^{\circ}C & 0.018 & \\ \hline V_{GS} = 10 V, I_{D} = 20 A, T_{J} = 175 \ ^{\circ}C & 0.018 & \\ \hline V_{GS} = 4.5 V, I_{D} = 15 A & 0.013 & \\ \hline V_{GS} = 4.5 V, I_{D} = 20 A & 60 & \\ \hline \hline Dynamic & & & & & & & & & & & & & & & & & & &$			V _{GS} = 10 V, I _D = 20 A		0.011			
$ \begin{array}{ c c c c c } \hline \begin{tabular}{ c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$		Б	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.014		0	
$ \begin{array}{ c c c c c c } \hline Forward Transconductance^b & g_{fs} & V_{DS} = 15 \ V, \ I_D = 20 \ A & 60 & \hline \\ \hline \ Dynamic & & & & & & & & & & & & & & & & & & &$	Drain-Source On-State Resistance [®]	TDS(on)	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.018			
$ \begin{array}{ c c c c c c } \hline \text{Dynamic} & \hline \text{Dynamic} & \hline \text{Dynamic} & \hline \text{Dynamic} & \hline \text{Input Capacitance} & \hline C_{iss} & \\ \hline \text{Output Capacitance} & \hline C_{oss} & \\ \hline \text{Output Capacitance} & \hline C_{rss} & \\ \hline \text{Reverse Transfer Capacitance} & \hline C_{rss} & \\ \hline \text{Total Gate Charge}^c & \hline Q_g & \\ \hline \text{Gate-Source Charge}^c & \hline Q_{gd} & \\ \hline \text{Gate-Source Charge}^c & \hline Q_{gd} & \\ \hline \text{Gate-Drain Charge}^c & \hline Q_{gd} & \\ \hline \text{Turn-On Delay Time}^c & \hline t_{d(on)} & \\ \hline \text{Rise Time}^c & \hline t_r & \\ \hline \text{V}_{DD} = 30 \text{ V}, \text{R}_{\text{L}} = 0.6 \Omega & 10 & 20 & \\ \hline \text{Rise Time}^c & \hline t_f & \\ \hline \text{Source-Drain Diode Ratings and Characteristics (T_{\text{C}} = 25 \text{ °C})} & \hline \text{Pulsed Current} & \hline I_{\text{SM}} & \hline \text{I}_{\text{F}} = 20 \text{ A}, \text{V}_{\text{GS}} = 0 \text{ V} & 1 & 1.5 & \\ \hline \end{array} $			V _{GS} = 4.5 V, I _D = 15 A		0.013			
$ \begin{array}{ c c c c c c } \hline \mbox{Input Capacitance} & C_{iss} & V_{GS} = 0 \ V, \ V_{DS} = 25 \ V, \ f = 1 \ MHz & 4200 & & & \\ \hline \mbox{Output Capacitance} & C_{rss} & V_{GS} = 0 \ V, \ V_{DS} = 25 \ V, \ f = 1 \ MHz & 570 & & & \\ \hline \mbox{325} & & & & & \\ \hline \mbox{Total Gate Charge}^{\circ} & Q_{g} & & & & & & & & \\ \hline \mbox{Total Gate Charge}^{\circ} & Q_{g} & & & & & & & & & & \\ \hline \mbox{Gate-Source Charge}^{\circ} & Q_{gd} & & & & & & & & & & & & \\ \hline \mbox{Gate-Drain Charge}^{\circ} & Q_{gd} & & & & & & & & & & & & & & \\ \hline \mbox{Gate-Drain Charge}^{\circ} & Q_{gd} & & & & & & & & & & & & & & & \\ \hline \mbox{Turn-On Delay Time}^{\circ} & \mbox{t}_{d(on)} & & & & & & & & & & & & & & & & & & \\ \hline \mbox{Rise Time}^{\circ} & \mbox{t}_{f} & & & & & & & & & & & & & & & & \\ \hline \mbox{Turn-Off Delay Time}^{\circ} & \mbox{t}_{d(off)} & & & & & & & & & & & & & & & & & & &$	Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
$ \begin{array}{ c c c c c } \hline Output Capacitance & C_{oss} & V_{GS} = 0 \ V, \ V_{DS} = 25 \ V, \ f = 1 \ MHz & 570 & 325 & $	Dynamic							
Reverse Transfer Capacitance C_{rss} 325 Total Gate Charge° Q_g 47 47 Gate-Source Charge° Q_{gs} $V_{DS} = 30 V, V_{GS} = 10 V, I_D = 50 A$ 10 12 Gate-Drain Charge° Q_{gd} 12 10 20 Turn-On Delay Time° $t_{d(on)}$ $V_{DD} = 30 V, R_L = 0.6 \Omega$ 15 25 Turn-Off Delay Time° $t_{d(off)}$ $V_{DD} = 50 A, V_{GEN} = 10 V, R_g = 2.5 \Omega$ 15 25 Fall Time° t_f $V_D = 50 A, V_{GEN} = 10 V, R_g = 2.5 \Omega$ 20 30 Source-Drain Diode Ratings and Characteristics ($T_C = 25 °C$) 20 30 60 Pulsed Current I_{SM} $I_F = 20 A, V_{GS} = 0 V$ 1 1.5	Input Capacitance	C _{iss}			4200			
$ \begin{array}{c c c c c c c } \hline Total Gate Charge^{\circ} & Q_{g} & & & & & & & & & & & & & & & & & & &$	Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		570		pF	
$ \begin{array}{c c c c c c c c c } \hline Gate-Source Charge^c & Q_{gs} & V_{DS} = 30 \ V, \ V_{GS} = 10 \ V, \ I_D = 50 \ A & 10 & 12 & 12 & 12 & 12 & 12 & 12 & 12$	Reverse Transfer Capacitance	C _{rss}			325			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Total Gate Charge ^c	Qg			47			
$ \begin{array}{c c c c c c c c } \hline Turn-On \ Delay \ Time^{\circ} & t_{d(on)} & & & & & & & & & & & & & & & & & & &$	Gate-Source Charge ^c	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 50 A		10		nC	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Drain Charge ^c	Q _{gd}			12			
$\begin{tabular}{ c c c c c c c } \hline Turn-Off Delay Time^{\circ} & t_{d(off)} \\ \hline Fall Time^{\circ} & t_{f} & & & & & & & & & & & \\ \hline Source-Drain Diode Ratings and Characteristics (T_{C} = 25 \ ^{\circ}C) & & & & & & & & & & & & \\ \hline Pulsed Current & I_{SM} & & & & & & & & & & & & & & & \\ \hline Diode Forward Voltage & V_{SD} & I_{F} = 20 \ A, \ V_{GS} = 0 \ V & & & & & 1 & & 1.5 \\ \hline \end{array}$	Turn-On Delay Time ^c	t _{d(on)}			10	20		
Fall TimeIdditionIdditionIdditionFall Time t_f 2030Source-Drain Diode Ratings and Characteristics ($T_C = 25 \ ^{\circ}C$)Pulsed Current I_{SM} 60Diode Forward Voltage V_{SD} $I_F = 20 \ A, V_{GS} = 0 \ V$ 1	Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_{L} = 0.6 \Omega$		15	25	ns	
Source-Drain Diode Ratings and Characteristics ($T_C = 25 \degree C$)Pulsed Current I_{SM} 60Diode Forward Voltage V_{SD} $I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$ 1	Turn-Off Delay Time ^c	t _{d(off)}	$I_D{\cong}50$ A, V_{GEN} = 10 V, R_g = 2.5 Ω		35	50		
Pulsed Current I _{SM} 60 Diode Forward Voltage V _{SD} I _F = 20 A, V _{GS} = 0 V 1 1.5	Fall Time ^c	t _f			20	30		
Diode Forward Voltage V_{SD} $I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$ 11.5	Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)					
	Pulsed Current					60	А	
Reverse Recovery Time t_{rr} $I_F = 20 \text{ A}$, di/dt = 100 A/µs45100	Diode Forward Voltage	V _{SD}	I _F = 20 A, V _{GS} = 0 V		1	1.5	V	
	Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		45	100	ns	

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

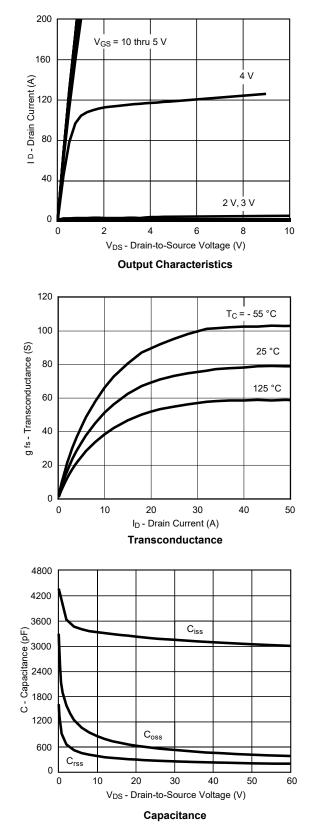
c. Independent of operating temperature.

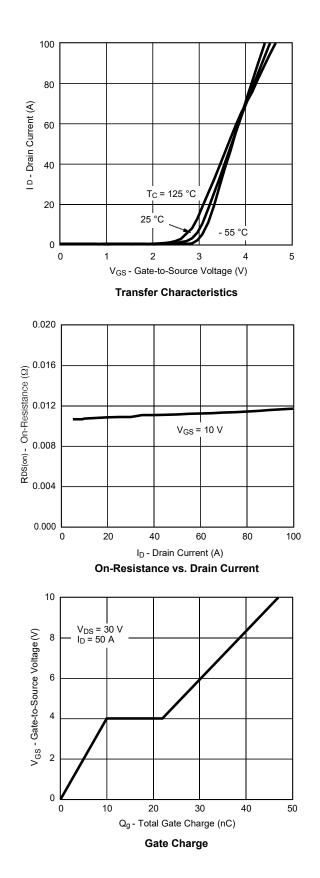
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Bsemi



TYPICAL CHARACTERISTICS (25 °C unless noted)

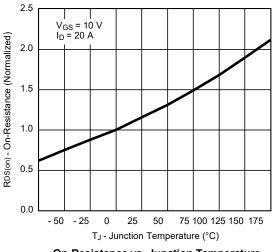




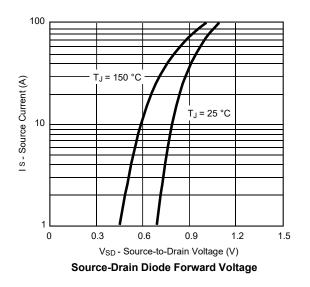
服务热线:400-655-8788



TYPICAL CHARACTERISTICS (25 °C unless noted)

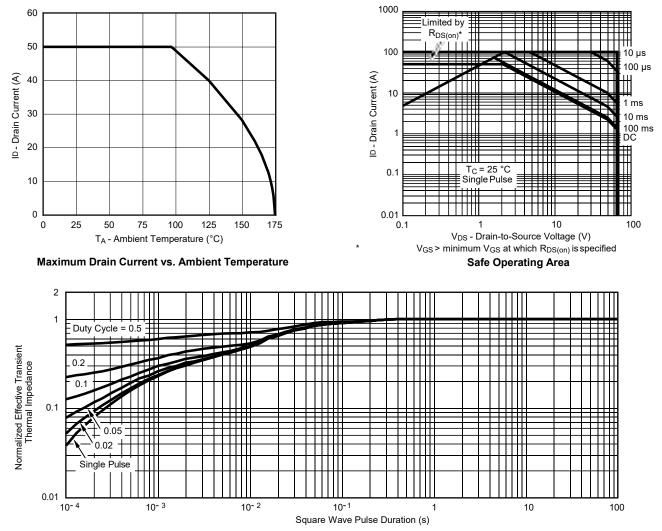


On-Resistance vs. Junction Temperature



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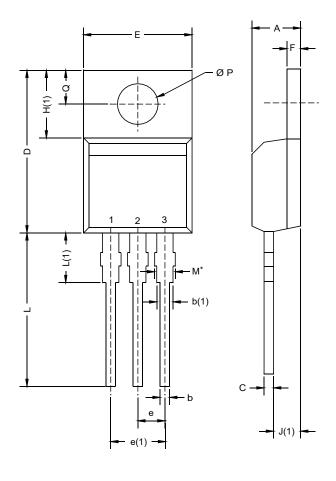
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



DIM.	MILLIM	ETERS	INC	INCHES		
	MIN.	MAX.	MIN.	MAX.		
А	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
Е	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: X15- DWG: 603	0364-Rev. C, 1	14-Dec-15				

Note

• M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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